深圳市丰泰盛电子科技有限公司

SPECIFICATION

(产品规格书)

CUSTOMER :_____
(客 户)
PART NO. :_____
(产品型号)
SPEC NO. :_____
(规格书编号)
DESCRIPTION :**1W 粉红**光_____
(产品描述)
DATE :_____
(日期)

R&D DEPARTMENT (技术部)		
APPROVED (核准)	CHECKED (审核)	PREPARED (制定)

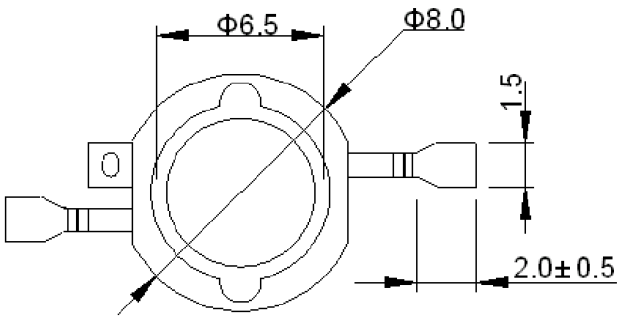
■ Feature
(特 性)

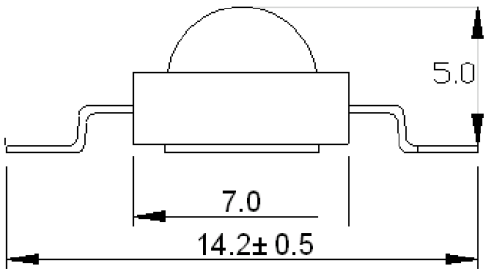
- ◆ ١W High Power LED
  (١W 大功率 LED)
- ◆ Package : SMT Package
  (贴片式外形)
- ◆Half Angle (٢Θ١/٢):١4٠°
  (视角：١4٠°)
- ◆Lens Color : Water Clear
  (透镜颜色：无色透明)

■ Applications
(应 用)

- ◆ General Linghting
  (普通照明)
- ◆ Advertisement
  (广告灯)
- ◆Architectural Lighting
  (建筑照明)
- ◆ Street Lamps
  (路 灯)

■ Package Dimensions
(外观尺寸)





Notes:

١. All dimensions are in millimeters.
(所有尺寸以毫米为单位)

٢. Tolerance is ±٠.٢٥ unless otherwise noted
(未标注公差为：±٠.٢٥)

Part NO. (产品型号)	LED Chip		LED Emitted Color (LED 发光颜色)	Lens Color (透镜颜色)	Description (描述)
	Material (材质)	Emitted Color (发光颜色)			
1W 粉红光 33miu 晶元	InGaN /GaN	Pink(粉红色)	Pink (粉红)	Clear(透明)	Water Clear (无色透明)

■ Electrical/Optical Characteristics (At T_A=25°C)
(光 电 参 数)

Parameter (参数)	Symbol (符号)	Conditions (测试条件)	Min. (最小值)	Avg. (平均值)	Max. (最大值)	Units (单位)
Luminous Flux (发光强度)	Φ	I_F=350mA	100	--	110	lm
Dominant Wavelength (色温)	DW	I_F=350mA	--	--	--	K
Forward Voltage (正向压降)	V_F	I_F=350mA	3.0	--	3.6	V
Thermal Resistance Junction To Board (热 阻)	$R\Theta_{J-B}$	I_F=350mA	- -	10	- -	°C/W
Reverse Current (反响漏电流)	I_R	V_R=5V	- -	- -	1	μA
Viewing Angle [1] (发光角度)	$2\Theta_{1/2}$	I_F=350mA	- -	140	- -	Deg

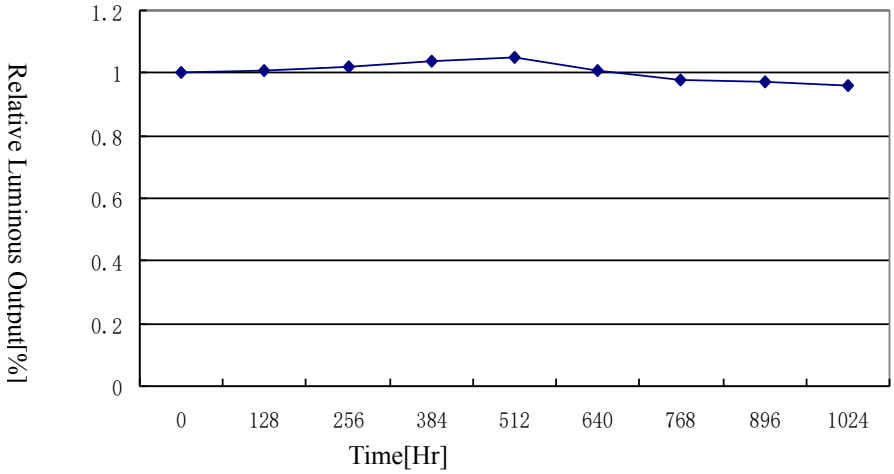
■ Absolute Maximum Rating(At TA=25°C)
(极 限 参 数)

Parameter (参数)	Symbol (符号)	Ratings (数值)	Units (单位)
Power Dissipation (功率)	P_D	1	W
Continuous Forward Current (正向输入电流)	I_F	350	mA
LED Junction Temperature (结点温度)	T_J	120	°C
Reverse Voltage (反向电压)	V_R	5	V
Operating Temperature Range (工作温度)	T_{OPR}	-30°C To +60°C	
Storage Temperature Range (储存温度)	T_{STG}	-40°C To +100°C	
Manual Solding Temperature (手工焊接温度)	T_{SOL}	350°C± 20°C For 3~5 Seconds	
ESD Sensitivity (抗静电能力)	ESD	2000V HBM	

Room Temperature Operating Life Reliability Test Result

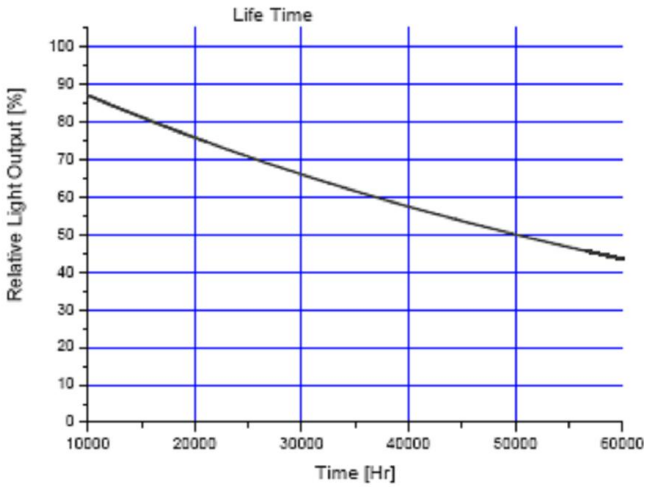
常温点亮信耐性结果

(Ta=25°C,If=350mA)Use SSC circuit board&heat sink(Tj=50°C)
使用 SSC 带热沉电路板(Tj=50°C)



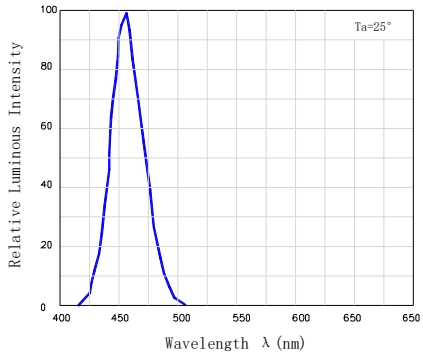
١٠٠٠HR 2.٥％ degradation(1000 小时衰减 2.5%)

Life Time graph (使用寿命)

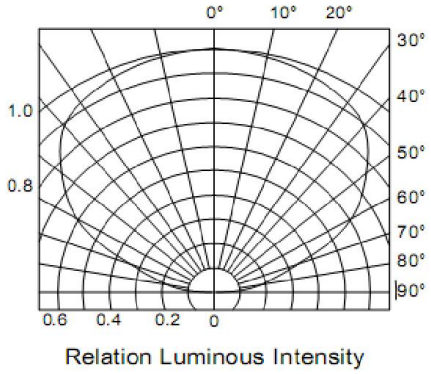


50···HR 50％ degradation (50000 小时衰减 50%)

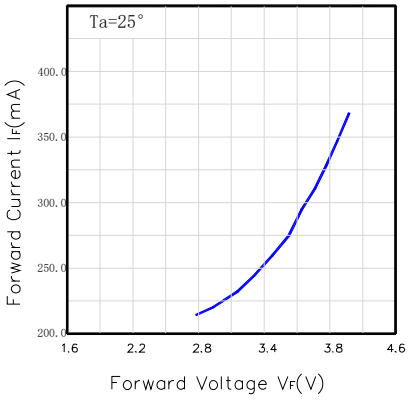
Spectrum Distribution(光谱分布图)



Radiation Diagram(角度图)



V_F-I_F Characteristics(V_F-I_F 曲线)



Precautions For use

(١) Storage

In order to aviod absorption of moisture it is recommended that the products are stored in the dry box (or dessicator) with a dessicant.Alternatively the following environment is recommended:
Storage temperature :٥°C~٣٠°C Humidity:٦٠% HR max.

(2) Any mechanical force or any excess vibration should be avoied during the cooling process after soldering.
(3) Components should not be mounted on distorted Printed Circuit Boards.
(4) Devices should not be used in any type of fluid such as water,oil,organic solvents etc. When cleaning is required,IPA should be used.
(5) Devices should be soldered within ٧ days after opening the moisture-proof packing.
(6) ESD Precautions.Static Electricity and surge damages LEDs.

It is recommended that wrist bands or anti-electrostatic gloves be used when handing the LEDs.All devices,equipment and machinery should be properly grounded.

(7) It is recommended to use individual resistors when LEDs are used in parallel circuits in order to improve performance.

使 用 说 明

一、贮存：

为避免吸潮建议将产品贮存在放有干燥剂的干燥柜中，贮存温度为：5℃~30℃，湿度：≤60%HR。

二、产品在焊锡后冷却过程中避免机械压力和过大震动。

三、禁止焊接在变形PCB板上。

四、产品不得接触水、油、有机溶液。

五、打开防潮包装后7天内产品使用完毕。

六、防静电要求：

使用产品时，必须戴防静电环或防静电手套，所有设备、装置、机台必须有效接地。

七、将产品与电阻配合使用效果更佳